EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	36	inspect$3 and(wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:23
L2	1	L1 and(pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
L3	0	L2 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
L4	0	L2 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:25
L5	23	((HUNG-EN) near2 (TAI)).INV.	US-PGPUB; USPAT	OR	ON	2008/05/13 14:26
L6	4	((CHIA-YUN) near2 (CHEN)). INV.	US-PGPUB; USPAT	OR	ON	2008/05/13 14:27
L7	1	L5 and(pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:27
L8	1	L6 and(pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:27
L9	1	L5 and inspect$3 and(wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:28

L10	1	(performing or obtaining)same (pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:29
L11	11	(performing or obtaining)same (pre adj treatment or pre-treatment)and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:30
L12	1	L11 and server and (generat $3 or obtaining)and drawing adj files	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:32
L13	7	L11 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:33
L14	1	L11 and server and (generat $3 or obtaining)and(drawing or sketch$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:33
L15	0	L13 and server and (generat $3 or obtaining)and(drawing or sketch$3 or geometric)and (image$1 or file)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:34
L16	6	L13 and(generat$3 or obtaining)and(drawing or sketch$3 or geometric)and (image$1 or file)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:34
L17	0	L16 and server	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:35
L18	6	L13 and(generat$3 or obtaining)and(drawing or sketch$3 or geometric)and (image$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:37

L19	7	(performing or obtaining)same (pre adj treatment or pre-treatment)and(wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:45
L20	2	L19 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:45
L21	1	server adj integrat$3 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:47
L22	869	inspect$3 and (wafer$1 or semicondudor$I or chip$I or substrat$I or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:48
L23	1	L22 and(performing or obtaining)same(pre adj treatment or pre-treatment) and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:49
L24	606	L22 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:49
L25	0	L24 and(performing or obtaining)and(pre adj treatment or pre-treatment) and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50
L26	0	L24 and(pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50
L27	8	L24 and(pre adj treatment or pre-treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:50

L28	0	L27 and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:53
L29	15	manag$3 and wafer$1 adj defects and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:54
L30	12	L29 and @ad< "20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:54
L31	10	L30 and(generat$3 or obtaining)and(drawing or sketch$3 or geometric)and (image$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:55
L32	0	L31 and(pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:56
L33	0	L31 and(pre adj treatment or pre-treatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:56
L34	0	L31 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:57
L35	8	L31 and(generat$3 or obtaining)and distribut$3 adj data and record$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 14:58
L36	10	inspect$3 and wafer$1 adj defects and server and integrate and wafer$1 adj defect$3 and(generat$3 or obtaining)and distribut$3 adj data and record$3	US-PGPUB; USPAT; EPO; JPO; IBM_TDB	OR	ON	2008/05/13 15:02
L37	8	L36 and @ad< "20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:02

L38	23	L1 and(generat$3 or obtaining)and(drawing or sketch$3 or geometric)and (image$1 or file)and position and type and size and(display or screen)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:04
L39	5	L38 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:05
L40	0	L39 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:15
L41	1	L38 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:16
L42	2	generat$4 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:18
L43	0	L42 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:18
L44	1	L38 and generat$4 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:19
L45	1	L38 and inspect$3 and wafer $1 adj defects and server and integrat$4 and wafer$1 adj defect$3 and(generat$3 or obtaining)and distribut$3 adj data and record$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21
L46	0	L45 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21
L47	2	inspect$3 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:21

L48	0	L47 and @ad< "20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:22
L49	527773	inspect$3 drawings adj files and wafer adj defect and (wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat $3 adj defect$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:23
L50	1	inspect$3 and drawings adj files and wafer adj defect and (wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat $3 adj defect$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:23
L51	0	chip adj grid and inspect$3 and(plurality or plural$1)same inspect$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:27
L52	29	inspect$3 and(chip adj grid or wafer$1 or semicondudor$1 or chip$1 or substrat$1 or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat $3 adj defect$3 and (plurality or plural$1)same stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
L53	25	L52 and @ad< "20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
L54	0	L53 and inspect$3 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:31
L55	0	L53 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:32

L56	0	L53 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:32
L57	0	L53 and inspect$3 and wafer $1 adj defects and server and integrat$4 and wafer$1 adj defect$3 and(generat$3 or obtaining)and distribut$3 adj data and record$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:33
L58	0	L53 and wafer$1 adj defects and server and integrat$4 and wafer$1 adj defect$3 and (generat$3 or obtaining)and distribut$3 adj data and record $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:33
L59	0	L53 and server and integrat$4 and wafer$1 adj defect$3 and (generat$3 or obtaining)and distribut$3 adj data and record $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:34
L60	3	L53 and server and integrat$4 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:34
L61	0	L60 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:44
L62	0	L60 and wafer$1 adj defects and server and integrat$4 and wafer$1 adj defect$3 and (generat$3 or obtaining)and distribut$3 adj data and record $3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:48
L63	0	L60 and(generat$3 or obtaining)and distribut$3 adj data and record$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:49
L64	0	L60 and(chip adj grid or cells or blocks)and inspect$3 and (plurality or plural$1)same inspect$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:50
L65	606	(chip adj grid or cells or blocks)and inspect$3 and (plurality or plural$1)same inspect$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51

L66	0	L65 and server and integrat$4 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51
L67	2	L65 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:51
L68	0	L67 and @ad< "20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:52
L69	0	L52 and drawings adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53
L70	29	L52 and generat$3 adjfiles and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53
L71	0	L52 and generat$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:53
L72	0	L52 and generat$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:54
L73	0	L65 and generat$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55
L74	0	L65 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55
L75	0	L65 and files and wafer adj defect and position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:55

L76	0	L65 and generat$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
L77	24	generat$3 adj files and wafer adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
L78	51	generat$3 and files and wafer adj defect same position and size and type	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
L79	32	L78 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:56
L80	11	L79 and server and integrat$4 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57
L81	0	L80 and(chip adj grid or cells or blocks)and inspect$3 and (plurality or plural$1)and inspect$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57
L82	0	L80 and(plurality or plural$1) and inspect$3 adj stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:57
L83	2	L80 and(plurality or plural$1) and stations	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:58
L84	2	L83 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 15:58
L85	2	L84 and(subtract$3 or difference)and defect adj position	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:00

L86	1	L84 and(subtract$3 or difference)and defect adj position and generat$3 adj data and new adj defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:02
L87	0	L86 and(pre adj treatment or pre-treatment or pretreatment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/05/13 16:04
S1	2	"6763130".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 11:51
S2	25	inspect$3 and (wafer$1 or semicondudor$l or chip$l or substrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3 and raw adj data	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 11:59
S3	14	S2 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:18
S5	0	S3 and (pre adj treatment or pre-treatment)and server and integrate same wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:12
S6	0	S3 and (pre adj treatment or pre-treatment)and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:12
S7	0	S3 and server adj integrate with wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:13
S8	0	S3 and server adj integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S9	0	S3 and server adj integrat$3 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:14

S10	1	S2 and server adj integrat$3 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:14
S11	1	inspect$3 and (wafer$1 or semicondudor$l or chip$l or substrat$l or IC or intergrated adj circuit or PCB or printed adj circuit adj board or PWB or printed adj wiring adj board)and generat$3 adj defect$3 and raw adj data and server adj integrat$3 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:16
S12	3	S2 and server and integrat$3 and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S13	0	S3 and server and integrate and wafer$1 adj defect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:17
S14	2	S12 and (@ad<"20040909" or @rlad<"20040909" or @prad<"20040909" or @ptad<"20040909")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 12:18
S15	2	S12 and @ad<"20040909"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 13:56
S16	2	"7103210".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/06 13:56

5/ 13/ 08 4:05:30 PM
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